#### Lead free compatible

Hi-Tg high thermal reliability for Lead free compatible laminate and prepreg

# TU-768, TU-768P

TU-768/ TU-768P laminate/ prepreg are made of high quality woven E-glass coated with the epoxy resin system, which provides the laminates with UV-block characteristic, and compatibility with automated optical inspection (AOI) process. These products are suitable for boards that need to survive severe thermal cycles, or to experience excessive assembly work. TU-768 laminates exhibit excellent CTE, superior chemical resistance and thermal stability plus CAF resistance property.

### PERFORMANCE AND PROCESSING ADVANTAGES

- · Lead Free process compatible
- · Excellent coefficient of thermal expansion
- · Anti-CAF property
- · Superior chemical and thermal resistance
- · Fluorescence for AOI
- Moisture resistance

#### **GENERAL INFORMATION**

· Industry Approvals

UL Designation - ANSI Grade FR-4
UL File Number E189572
Flammability Rating 94V-0
Maximum Operating Temperature 130°C

· Standard Availability

Thickness: 0.002"[0.05mm] to 0.062"[1.58mm], available in sheet or panel form

 $Copper\ Foil\ Cladding:\ 1/8\ to\ 12oz\ (HTE)\ for\ built-up;\ 1/8\ to\ 3oz\ (HTE)\ for\ double\ sides\ and\ H\ to\ 2oz\ (MLS)$ 

Prepregs: Available in roll or panel form

Glass Styles: 106, 1080, 2113, 2116, 1506 and 7628, etc.

## TYPICAL PROPERTIES FOR TU-768 LAMINATES

PROPERTY	IPC-4101	SPEC	TYPICAL VALUES
Thermal			
Tg (DMA) Tg (DSC) Tg (TMA) Td (TGA)	E-2/105+des	N/A	190 °C 180 °C 170 °C 350 °C
CTE x-axis CTE y-axis CTE z-axis	Ambient to Tg Ambient to Tg 25 to 260°C	- - -	11~15 ppm/°C 11~15 ppm/°C 2.7 %
Thermal Stress, Solder Float , 288°C	A	> 10	> 60 sec
T-260 T-288	E-2/105+des	N/A	> 60 min > 15 min
Flammability	E-24/125+des	94V-0	94V-0
Electrical			
Permittivity (RC 50%) 1GHz ( HP 4291B ) 5GHz ( SPC method ) 10GHz ( SPC method )	C-24/23/50	< 5.4	4.3 4.3 4.3
Loss Tangent (RC 50%)  1GHz ( HP 4291B )  5GHz ( SPC method )  10GHz ( SPC method )	C-24/23/50	< 0.035	0.019 0.021 0.023
Volume Resistivity	C-96/35/90	> 106	$> 10^{10}  \mathrm{M}\Omega \!\cdot\! \mathrm{cm}$
Surface Resistivity	C-96/35/90	> 104	$> 10^8 \ M\Omega$
Electric Strength		>30 kV/mm	> 40 kV/mm
Dielectric Breakdown Voltage		>40 kV	> 50 kV
Mechanical			
Young's Modulus Warp Direction Fill Direction	-	G Pa	25 22
Flexural Strength Lengthwise Crosswise	A A	> 60,000 > 50,000	> 65,000 psi > 55,000 psi
Peel Strength 1.0 oz. Cu foil	A	> 4	7~9 lb/inch
Water Absorption	E-1/105+des+D-24/23	< 0.8	0.18 %

#### NOTE:

- 1. Property values are for information purposes only and are not guaranteed.
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.